

Wafer Level Packaging and MEMS sensors



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Abstract :

This talk will give an overview of MEMS technology (especially design, fabrication and PKG), give short insights into the current status of MEMS sensor in mobile applications. Many MEMS sensor & actuator are chosen as core components in mobile devices. Looking into the details, there are several key issues that why they play an important role. We focus on several MEMS devices like inertial sensor (accelerometer & gyroscope), SAW filter and image sensor.

Speaker's Biography :

Won-Kyu Jeung received his B.S. degree in Mechanical Engineering from Hanyang University in 1998. He received a Master's of Mechanical Engineering from Yonsei University in 2005. In 1998, he joined the R&D Institute in Samsung Electro- Mechanics Co., LTD. He is currently a senior research engineer at Central R&D Institute in Samsung Electro-Mechanics Co., LTD. His work has been in MEMS and its related devices for the past 10 years. His current research includes general micromachining, wafer level packaging for various devices and inertial sensors. He has published over 34 papers and has 13 patents to his credit.